



## **PRESS RELEASE**

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### **TechSearch International Explores Power Device Packaging and Assembly Trends**

Power devices are experiencing growth driven by demand in a variety of areas. TechSearch International projects a 4.3% growth in overall leadframe package shipments from 2017 to 2021 with stronger growth projected for Cu clip packages. Applications including energy generation and infrastructure, electric and hybrid vehicles, electric vehicle charging, datacenters, industrial automation, smart cities and buildings, home appliances, and transportation are driving demand for power devices. While many companies continue to expand production of silicon-based power devices, the need for increased power density and system efficiency is driving demand for devices based on new wide band gap (WBG) materials such as silicon carbide (SiC) and gallium nitride (GaN). The ramp of WBG devices will push operating junction temperatures to 200°C and beyond, and require new materials and assembly processes to deliver the necessary thermal and high current-carrying performance.

*New Packages and Materials for Power Devices* is a 100+ page report with full references and an accompanying set of more than 100 PowerPoint slides. Growth drivers and package types are identified. Key IDMs and OSATs that assemble WBG power devices are listed. Market projections for leadframe (including a breakdown of Cu clip) and embedded die packages are provided. Critical material needs for packaging and assembly are identified. New developments in die attach materials are described, with a focus on Pb-free options.

TechSearch International, Inc., founded in 1987, is a market research leader specializing in technology trends in microelectronics packaging and assembly. Multi- and single-client services encompass technology licensing, strategic planning, and market and technology analysis. TechSearch International professionals have an extensive network of more than 18,000 contacts in North America, Asia, and Europe. For more information, contact TechSearch at tel: 512-372-8887 or see [www.techsearchinc.com](http://www.techsearchinc.com). Follow us on twitter @Jan\_TechSearch